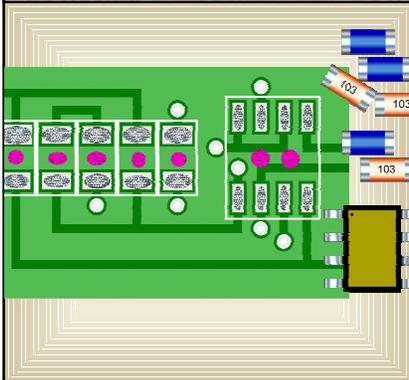


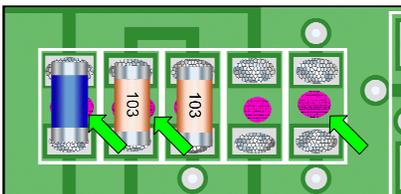
**SURFACE MOUNT TECHNOLOGY (SMT)  
ADHESIVE APPLICATION**



**ADHESIVE APPLICATION**

Adhesives are frequently used to temporarily hold SMT components in position prior to soldering. Once the soldering operations are completed, the adhesive residue is removed during the cleaning process.

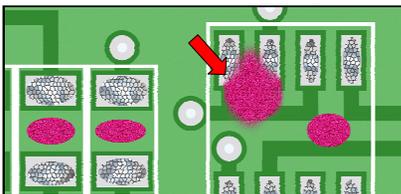
The application of adhesive should be controlled to ensure proper placement, amount, and cure. Excess adhesive, improper placement, or incomplete cure can contaminate solder paste and solderable surfaces, interfere with proper component alignment, and impact cleanability.



**PREFERRED**

The deposition of adhesive is consistent, properly placed, and repeatable. Dots are centered under the part body, equidistant between the land pattern areas.

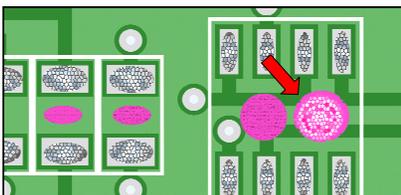
[NASA-STD-8739.2 \[ 8.9 \]](#), [\[ 8.10.2 \]](#)



**UNACCEPTABLE  
ADHESIVE ON LEADS / SOLDER PADS**

Adhesive deposits on part leads and/or solder pads interfere with proper placement, component retention, and solderability.

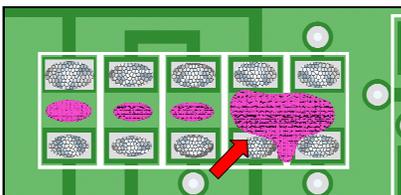
[NASA-STD-8739.2 \[ 8.10.3 \]](#)



**UNACCEPTABLE  
VOIDS**

Bubbles and voids in the adhesive reduce the deposit's cross-section and retention properties.

[NASA-STD-8739.2 \[ 8.9 \]](#), [\[ 8.10.1 \]](#)



**UNACCEPTABLE  
EXCESSIVE ADHESIVE**

Excessive adhesive interferes with proper placement, component retention, and solderability.

[NASA-STD-8739.2 \[ 8.10.3 \]](#)

**NASA WORKMANSHIP STANDARDS**



NATIONAL AERONAUTICS AND  
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JOHNSON SPACE CENTER  
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Released:  
06.27.2002

Revision:

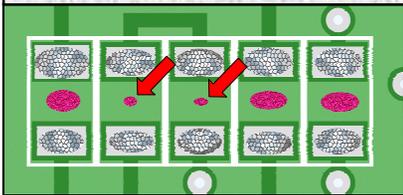
Revision Date:

Book:  
7

Section:  
7.03

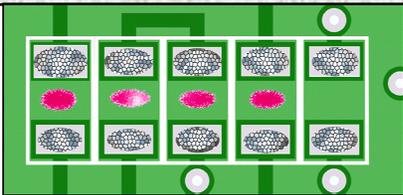
Page:  
1

**SURFACE MOUNT TECHNOLOGY (SMT)  
ADHESIVE APPLICATION (cont.)**



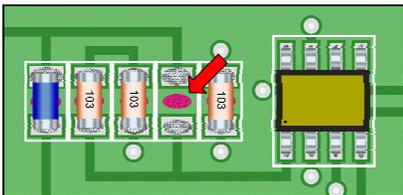
**UNACCEPTABLE  
INSUFFICIENT ADHESIVE**

Insufficient adhesive may result in lost and/or misaligned components, and increased rework.  
[NASA-STD-8739.2 \[ 6.15.1 \]](#), [\[ 8.9 \]](#)



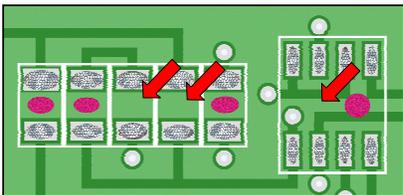
**UNACCEPTABLE  
INSUFFICIENT CURE**

Insufficiently cured adhesive may result in lost and/or misaligned components, and increased rework.  
[NASA-STD-8739.2 \[ 8.9 \]](#)



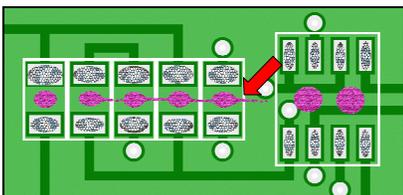
**UNACCEPTABLE  
LOST COMPONENTS**

Evidence of lost components indicates a process control problem (excessive / insufficient adhesive, insufficient cure, etc.).  
[NASA-STD-8739.2 \[ 6.15.4 \]](#)



**UNACCEPTABLE  
SKIPPING**

Skipping is an indicator of a process control problem, and may result in lost components and increased rework.  
[NASA-STD-8739.2 \[ 8.9 \]](#)



**UNACCEPTABLE  
STRINGING**

Stringing is an indicator of a process control problem, is a contaminant, and affects overall solderability.  
[NASA-STD-8739.2 \[ 6.15.1 \]](#)

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